FLIP-CHIP PROCESS BY PHOTO-CURING ADHESIVE

ABSTRACT OF THE DISCLOSURE

A flip-chip process includes the steps of disposing a plurality of spherical contact members on a surface of a wafer; forming a photo-curing adhesive layer on the surface of the wafer, wherein said photo-curing adhesive layer covers a part of each of the spherical contact members to expose the spherical contact members of the photo-curing adhesive layer; solidifying the photo-curing adhesive layer by exposure; cutting the wafer into a plurality of chip units; placing the chip units on a substrate to let the spherical contact members lie against contact points of the substrate; and pressurizing the chip units and then heating the spherical contact potions to enable the spherical contact members to be welded and electrically connected with the chip units and the contact points of the substrate.

FIGURE : 1